

## General Description

The GreenMOS® high voltage MOSFET utilizes charge balance technology to achieve outstanding low on-resistance and lower gate charge. It is engineered to minimize conduction loss, provide superior switching performance and robust avalanche capability.

The GreenMOS® S series is optimized for its switching characteristics to achieve aggressive EMI standards. It is easy to use for smaller power supply systems to meet the both efficiency and EMI standards.

## Features

- Low  $R_{DS(ON)}$  & FOM
- Extremely low switching loss
- Excellent stability and uniformity



## Applications

- LED lighting
- Charger
- Adapter
- Telecom power
- Server power
- Solar/UPS

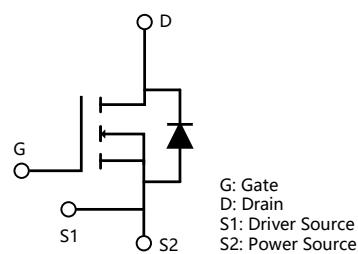
## Key Performance Parameters

| Parameter                      | Value | Unit |
|--------------------------------|-------|------|
| $V_{DS, min} @ T_{j(max)}$     | 650   | V    |
| $I_D, pulse$                   | 60    | A    |
| $R_{DS(ON), max} @ V_{GS}=10V$ | 200   | mΩ   |
| $Q_g$                          | 72.9  | nC   |

## Marking Information

| Product Name  | Package | Marking      |
|---------------|---------|--------------|
| OSG60R200JSZF | PDFN8*8 | OSG60R200JSZ |

## Package & Pin Information



**Absolute Maximum Ratings** at  $T_j=25^\circ\text{C}$  unless otherwise noted

| Parameter   | Symbol               | Value      | Unit             |
|---|----------------------|------------|------------------|
| Drain-source voltage  | $V_{DS}$             | 600        | V                |
| Gate-source voltage   | $V_{GS}$             | $\pm 30$   | V                |
| Continuous drain current <sup>1)</sup> , $T_C=25\text{ }^\circ\text{C}$         | $I_D$                | 20         | A                |
| Continuous drain current <sup>1)</sup> , $T_C=100\text{ }^\circ\text{C}$        |                      | 12.6       |                  |
| Pulsed drain current <sup>2)</sup> , $T_C=25\text{ }^\circ\text{C}$             | $I_{D,\text{pulse}}$ | 60         | A                |
| Continuous diode forward current <sup>1)</sup> , $T_C=25\text{ }^\circ\text{C}$ | $I_S$                | 20         | A                |
| Diode pulsed current <sup>2)</sup> , $T_C=25\text{ }^\circ\text{C}$             | $I_{S,\text{pulse}}$ | 60         | A                |
| Power dissipation <sup>3)</sup> , $T_C=25\text{ }^\circ\text{C}$                | $P_D$                | 151        | W                |
| Single pulsed avalanche energy <sup>5)</sup>                                    | $E_{AS}$             | 176        | mJ               |
| MOSFET dv/dt ruggedness, $V_{DS}=0\text{...}480\text{ V}$                       | dv/dt                | 50         | V/ns             |
| Reverse diode dv/dt, $V_{DS}=0\text{...}480\text{ V}$ , $I_{SD}\leq I_D$        | dv/dt                | 50         | V/ns             |
| Operation and storage temperature   | $T_{stg}, T_j$       | -55 to 150 | $^\circ\text{C}$ |

**Thermal Characteristics**

| Parameter  | Symbol          | Value | Unit               |
|--|-----------------|-------|--------------------|
| Thermal resistance, junction-case                  | $R_{\theta JC}$ | 0.83  | $^\circ\text{C/W}$ |
| Thermal resistance, junction-ambient <sup>4)</sup> | $R_{\theta JA}$ | 62    | $^\circ\text{C/W}$ |

**Electrical Characteristics** at  $T_j=25^\circ\text{C}$  unless otherwise specified

| Parameter                        | Symbol              | Min. | Typ. | Max. | Unit          | Test condition   |
|----------------------------------|---------------------|------|------|------|---------------|--|
| Drain-source breakdown voltage   | $BV_{DSS}$          | 600  |      |      | V             | $V_{GS}=0\text{ V}$ , $I_D=250\text{ }\mu\text{A}$                                   |
|                                  |                     | 650  |      |      |               | $V_{GS}=0\text{ V}$ , $I_D=250\text{ }\mu\text{A}$ , $T_j=150\text{ }^\circ\text{C}$ |
| Gate threshold voltage           | $V_{GS(\text{th})}$ | 3.0  |      | 4.5  | V             | $V_{DS}=V_{GS}$ , $I_D=250\text{ }\mu\text{A}$                                       |
| Drain-source on-state resistance | $R_{DS(\text{ON})}$ |      | 0.16 | 0.20 | $\Omega$      | $V_{GS}=10\text{ V}$ , $I_D=10\text{ A}$   |
|                                  |                     |      | 0.37 |      |               | $V_{GS}=10\text{ V}$ , $I_D=10\text{ A}$ , $T_j=150\text{ }^\circ\text{C}$           |
| Gate-source leakage current      | $I_{GSS}$           |      |      | 100  | nA            | $V_{GS}=30\text{ V}$   |
|                                  |                     |      |      | -100 |               | $V_{GS}=-30\text{ V}$  |
| Drain-source leakage current     | $I_{DSS}$           |      |      | 10   | $\mu\text{A}$ | $V_{DS}=600\text{ V}$ , $V_{GS}=0\text{ V}$  |
| Gate resistance                  | $R_G$               |      | 17.4 |      | $\Omega$      | $f=1\text{ MHz}$ , Open drain  |

### Dynamic Characteristics

| Parameter                    | Symbol              | Min. | Typ. | Max. | Unit | Test condition  |
|------------------------------|---------------------|------|------|------|------|---|
| Input capacitance            | C <sub>iss</sub>    |      | 1920 |      | pF   | V <sub>GS</sub> =0 V,<br>V <sub>DS</sub> =50 V,<br>f=100 kHz                                      |
| Output capacitance           | C <sub>oss</sub>    |      | 98.6 |      | pF   |   |
| Reverse transfer capacitance | C <sub>rss</sub>    |      | 2.3  |      | pF   |   |
| Turn-on delay time           | t <sub>d(on)</sub>  |      | 41.9 |      | ns   | V <sub>GS</sub> =10 V,<br>V <sub>DS</sub> =400 V,<br>R <sub>G</sub> =2 Ω,<br>I <sub>D</sub> =10 A |
| Rise time                    | t <sub>r</sub>      |      | 68.2 |      | ns   |   |
| Turn-off delay time          | t <sub>d(off)</sub> |      | 77.7 |      | ns   |   |
| Fall time                    | t <sub>f</sub>      |      | 33.9 |      | ns   |   |

### Gate Charge Characteristics

| Parameter            | Symbol               | Min. | Typ. | Max. | Unit | Test condition  |
|----------------------|----------------------|------|------|------|------|---|
| Total gate charge    | Q <sub>g</sub>       |      | 72.9 |      | nC   | V <sub>GS</sub> =10 V,<br>V <sub>DS</sub> =400 V,<br>I <sub>D</sub> =10 A |
| Gate-source charge   | Q <sub>gs</sub>      |      | 17.2 |      | nC   |   |
| Gate-drain charge    | Q <sub>gd</sub>      |      | 14   |      | nC   |   |
| Gate plateau voltage | V <sub>plateau</sub> |      | 6.5  |      | V    |   |

### Body Diode Characteristics

| Parameter                     | Symbol           | Min. | Typ. | Max. | Unit | Test condition  |
|-------------------------------|------------------|------|------|------|------|---|
| Diode forward voltage         | V <sub>SD</sub>  |      |      | 1.3  | V    | I <sub>S</sub> =20 A,<br>V <sub>GS</sub> =0 V                     |
| Reverse recovery time         | t <sub>rr</sub>  |      | 132  |      | ns   | V <sub>R</sub> =400 V,<br>I <sub>S</sub> =10 A,<br>di/dt=100 A/μs |
| Reverse recovery charge       | Q <sub>rr</sub>  |      | 730  |      | nC   |   |
| Peak reverse recovery current | I <sub>rrm</sub> |      | 10.8 |      | A    |   |

### Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of R<sub>θJA</sub> is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T<sub>a</sub>=25 °C.
- 5) V<sub>DD</sub>=100 V, V<sub>GS</sub>=10 V, L=79.9 mH, starting T<sub>j</sub>=25 °C.

## Electrical Characteristics Diagrams

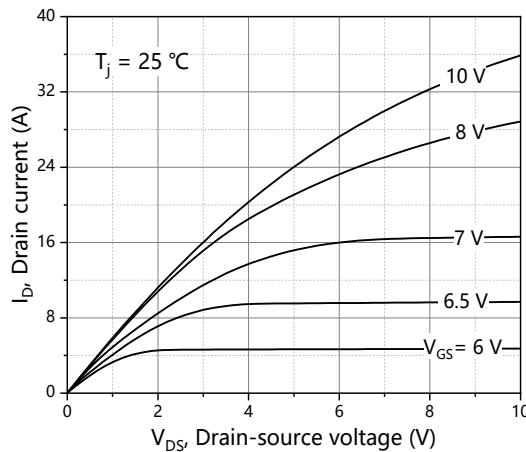


Figure 1. Typ. output characteristics

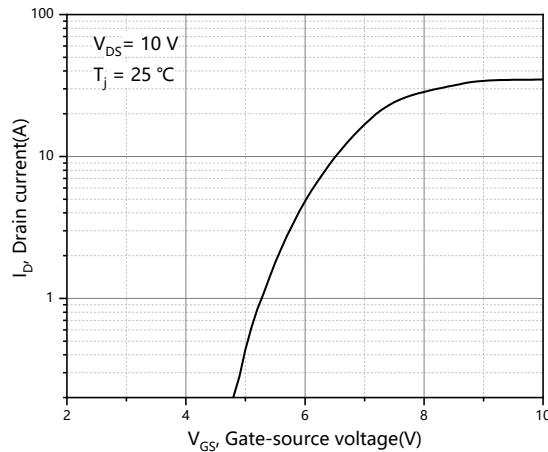


Figure 2. Typ. transfer characteristics

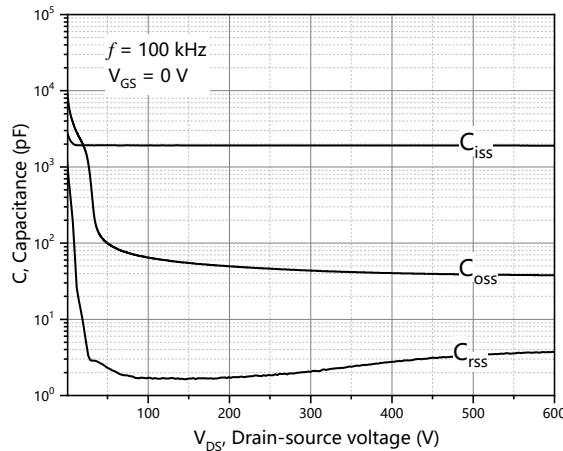


Figure 3. Typ. capacitances

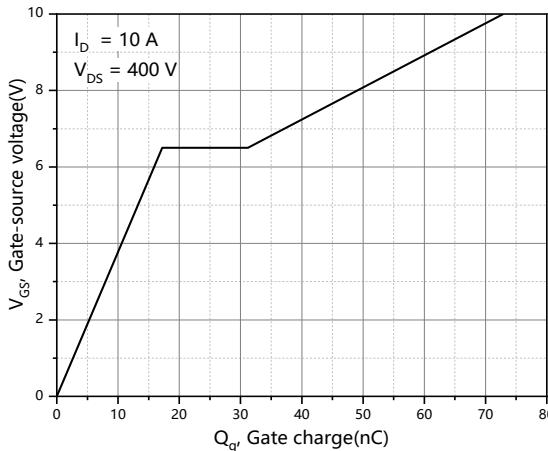


Figure 4. Typ. gate charge

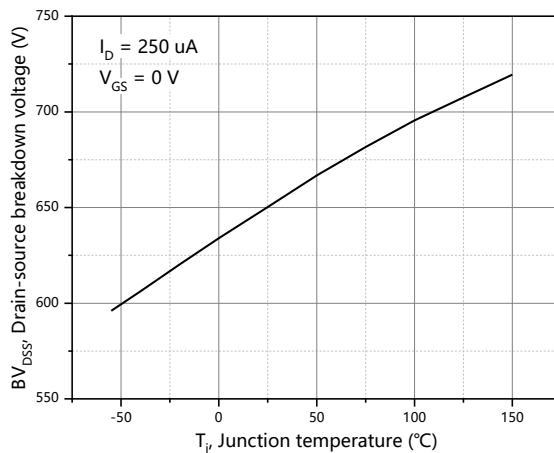


Figure 5. Drain-source breakdown voltage

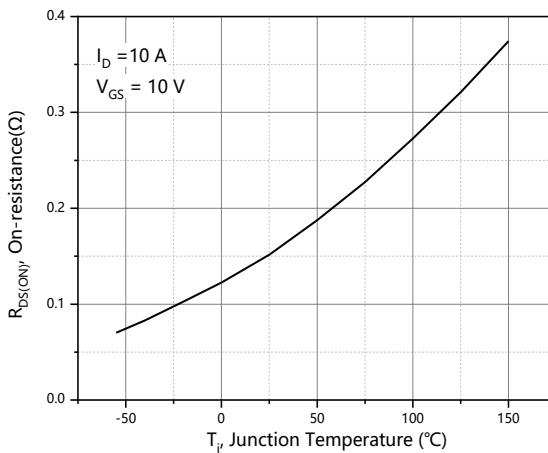
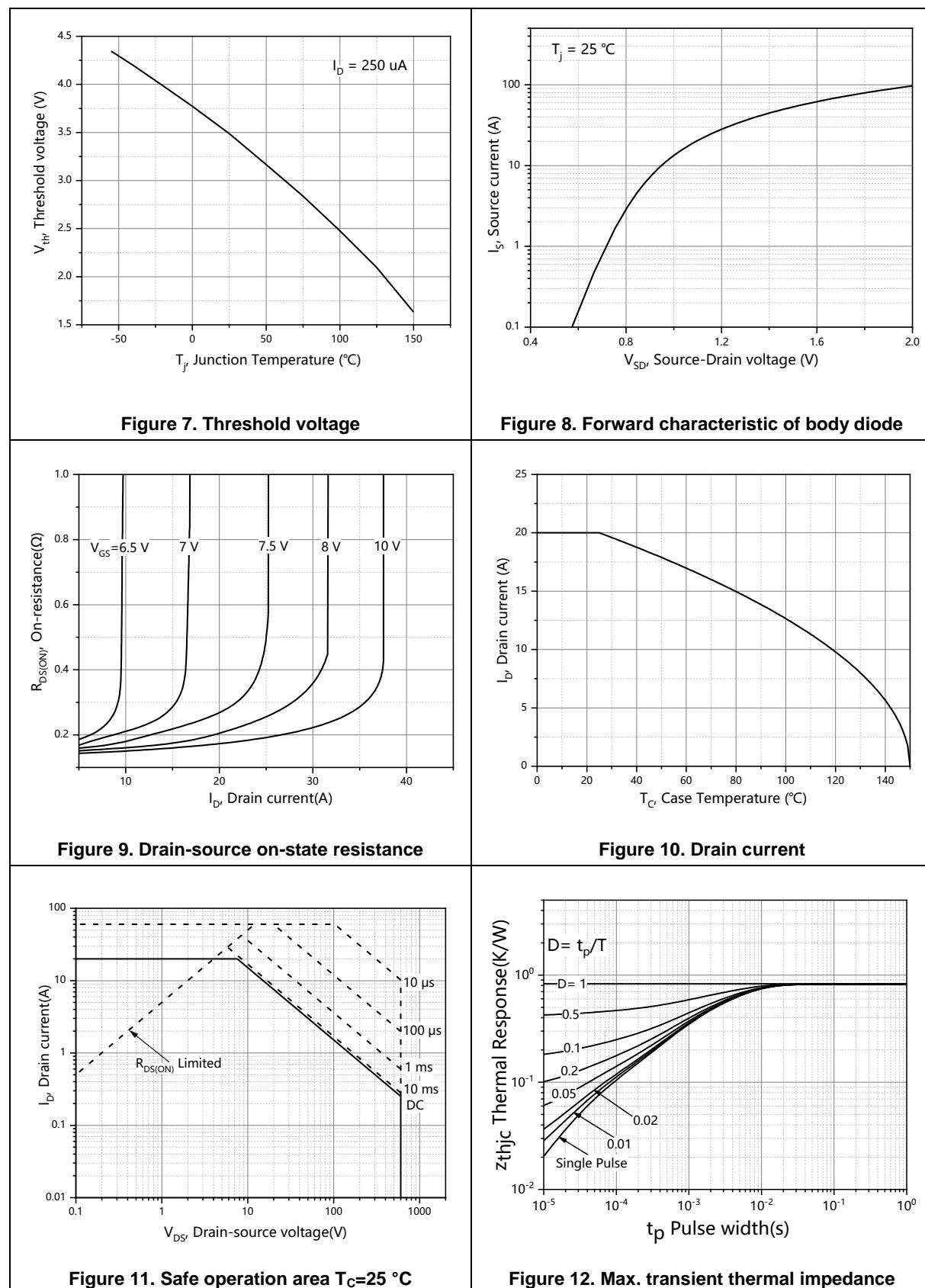


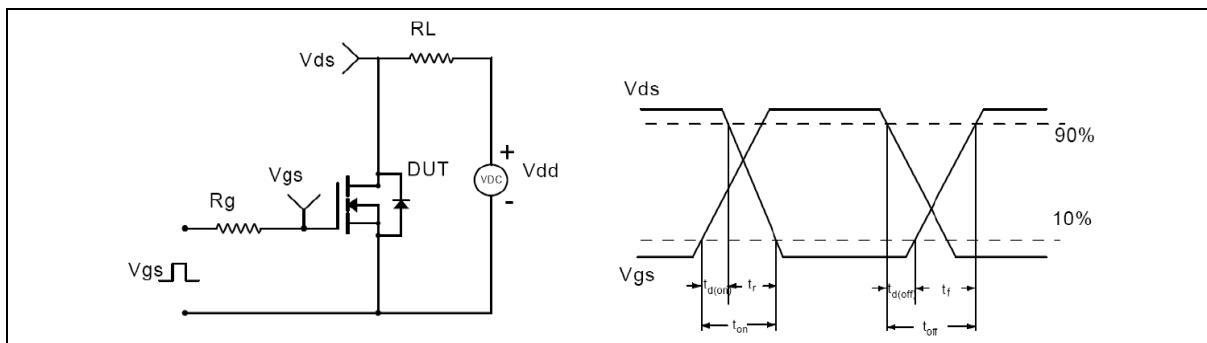
Figure 6. Drain-source on-state resistance



### Test circuits and waveforms



**Figure 1. Gate charge test circuit & waveform**



**Figure 2. Switching time test circuit & waveforms**

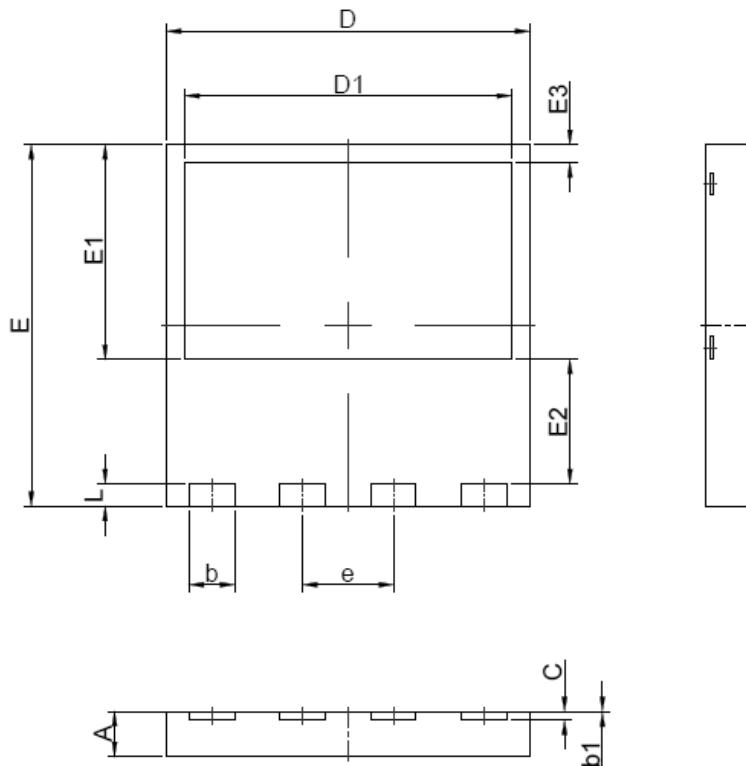


**Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms**



**Figure 4. Diode reverse recovery test circuit & waveforms**

### Package Information



| Symbol | mm      |      |      |
|--------|---------|------|------|
|        | Min     | Nom  | Max  |
| A      | 0.90    | 1.00 | 1.10 |
| b      | 0.90    | 1.00 | 1.10 |
| b1     | 0.00    | 0.02 | 0.05 |
| C      | 0.2 REF |      |      |
| D      | 7.90    | 8.00 | 8.10 |
| D1     | 7.10    | 7.20 | 7.30 |
| E      | 7.90    | 8.00 | 8.10 |
| E1     | 4.65    | 4.75 | 4.85 |
| E2     | 2.65    | 2.75 | 2.85 |
| E3     | 0.3     | 0.4  | 0.5  |
| e      | 2.0 BSC |      |      |
| L      | 0.4     | 0.5  | 0.6  |

Version 1: PDFN8\*8-L package outline dimension

## Ordering Information

| Package Type | Units/Reel | Reels/Inner Box | Units/Inner Box | Inner Boxes/Carton Box | Units/Carton Box |
|--------------|------------|-----------------|-----------------|------------------------|------------------|
| PDFN8*8-L    | 2500       | 1               | 2500            | 10                     | 25000            |

## Product Information

| Product       | Package | Pb Free | RoHS | Halogen Free |
|---------------|---------|---------|------|--------------|
| OSG60R200JSZF | PDFN8*8 | yes     | yes  | yes          |

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